

PROTECTION PRODUCTS - MicroClamp™

Description

The μ Clamp™ series of TVS arrays are designed to protect sensitive electronics from damage or latch-up due to ESD. It is designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and other portable electronics. It features large cross-sectional area junctions for conducting high transient currents. TVS diodes offer desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

The μ Clamp™0508T is in a 8-pin, RoHS/WEEE compliant, SLP1713P8T package. It measures 1.7 x 1.3 mm with a nominal height of only 0.4mm. The leads are spaced at a pitch of 0.4mm and are finished with lead-free NiPdAu. Each device features eight TVS diodes with an operating voltage of 5 volts and a maximum loading capacitance of only 10pF.

They may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (± 15 kV air, ± 8 kV contact discharge). The combination of small size and high ESD surge capability makes them ideal for use in portable applications such as cellular phones, digital cameras, and notebook computers.

Features

- ◆ Transient protection for data lines to **IEC 61000-4-2 (ESD) ± 15 kV (air), ± 8 kV (contact)**
IEC 61000-4-4 (EFT) 40A (tp = 5/50ns)
Cable Discharge Event (CDE)
- ◆ Ultra-small package
- ◆ Protects eight data lines
- ◆ Low clamping voltage
- ◆ Working voltage: 5V
- ◆ Low capacitance (10pF)
- ◆ Solid-state silicon-avalanche technology

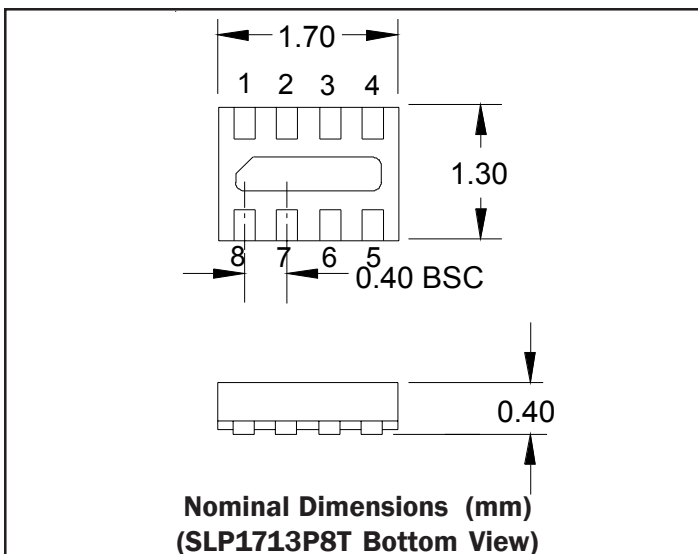
Mechanical Characteristics

- ◆ SLP1713P8T package
- ◆ RoHS/WEEE Compliant
- ◆ Nominal Dimensions: 1.7 x 1.3 x 0.4 mm
- ◆ Lead Finish: NiPdAu
- ◆ Molding compound flammability rating: UL 94V-0
- ◆ Marking : Marking code
- ◆ Packaging : Tape and Reel

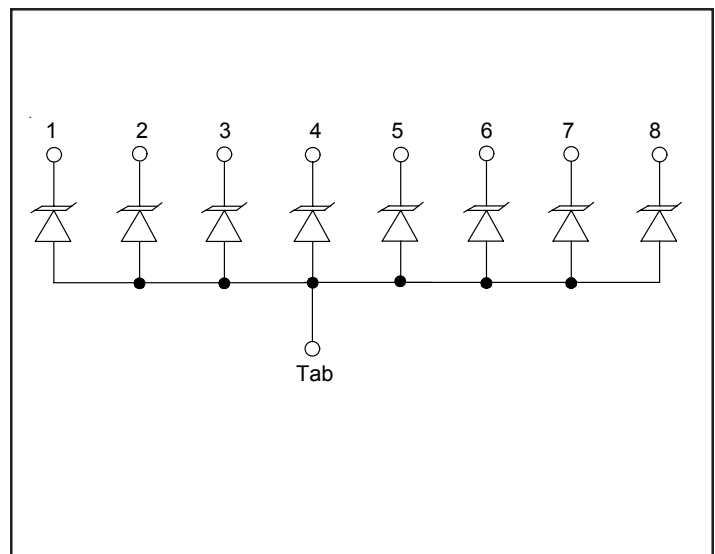
Applications

- ◆ Cellular Handsets & Accessories
- ◆ Notebooks & Handhelds
- ◆ Micro SD Ports
- ◆ MMC & HS-MMC Ports
- ◆ Portable Instrumentation
- ◆ Digital Cameras
- ◆ Peripherals

Dimensions



Schematic



PROTECTION PRODUCTS
Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{pk}	25	Watts
Maximum Peak Pulse Current ($t_p = 8/20\mu s$)	I_{pp}	2	Amps
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	+/- 20 +/- 15	kV
Operating Temperature	T_J	-55 to +125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

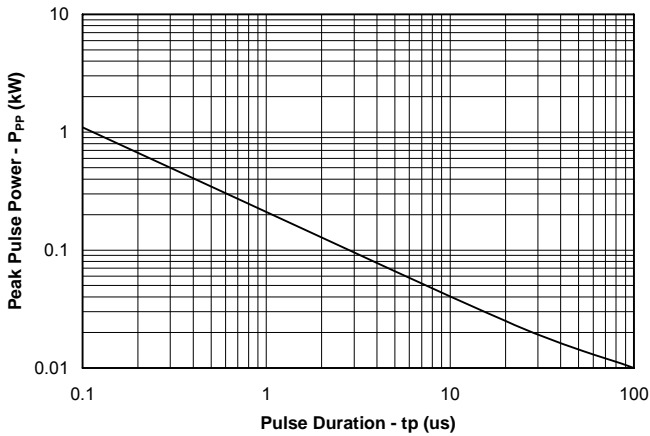
Electrical Characteristics (T=25°C)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				5	V
Reverse Breakdown Voltage	V_{BR}	$I_t = 1mA$	6			V
Reverse Leakage Current	I_R	$V_{RWM} = 5V, T=25^\circ C$			0.25	μA
Forward Voltage	V_F	$I_F = 10mA$		1	1.2	V
Clamping Voltage	V_C	$I_{pp} = 2A, t_p = 8/20\mu s$			12.5	V
Junction Capacitance	C_j	$V_R = 0V, f = 1MHz$			10	pF
Junction Capacitance	C_j	$V_R = 3.3V, f = 1MHz$		4.5		pF

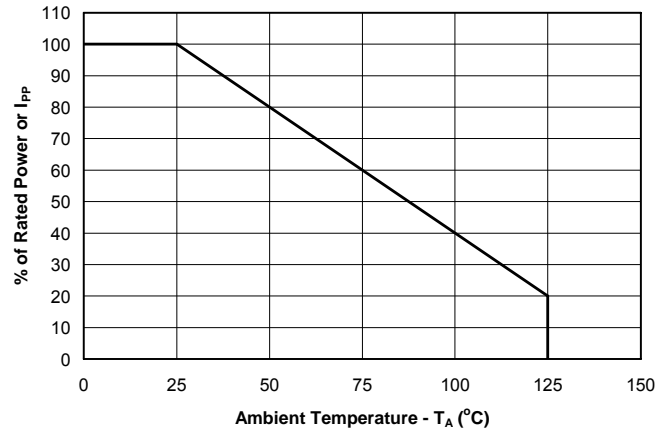
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Typical Characteristics

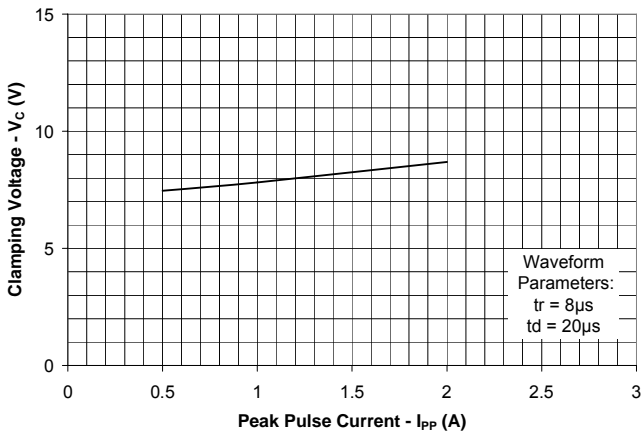
Non-Repetitive Peak Pulse Power vs. Pulse Time



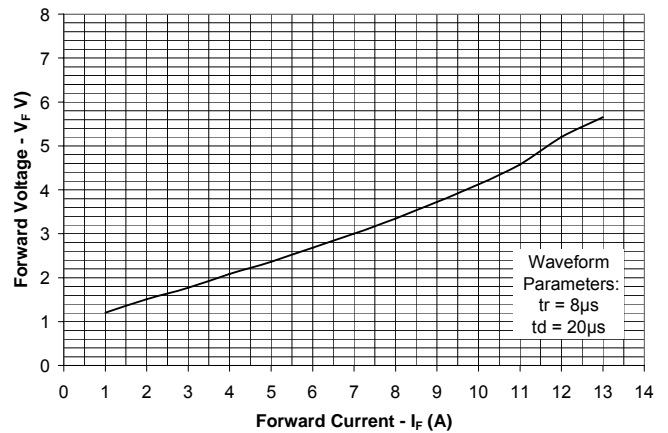
Power Derating Curve



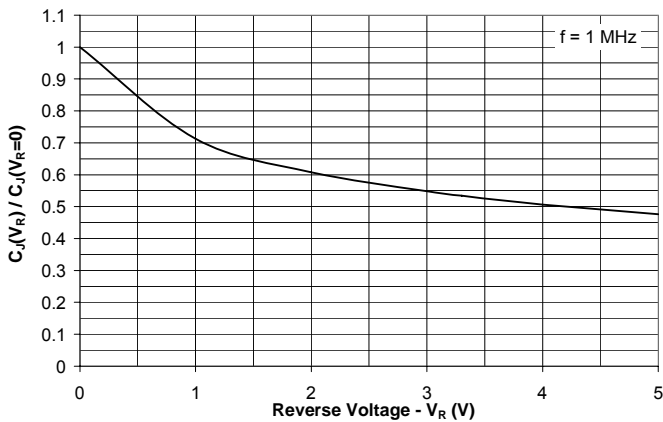
Clamping Voltage vs. Peak Pulse Current



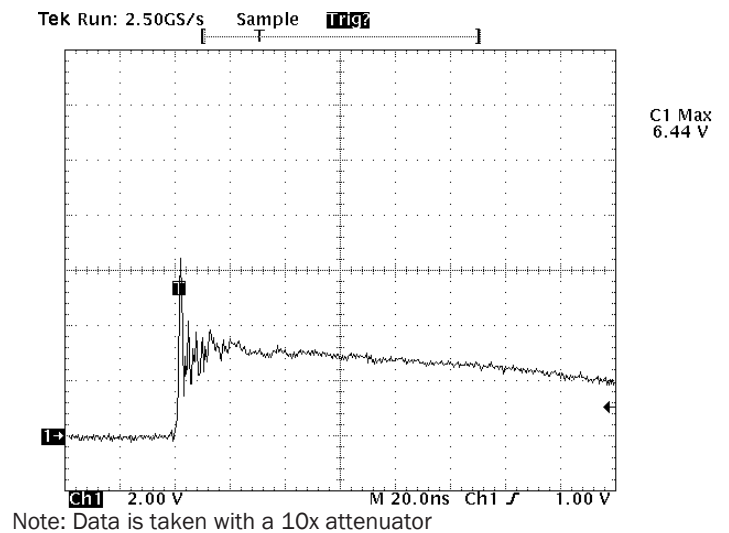
Forward Voltage vs. Forward Current

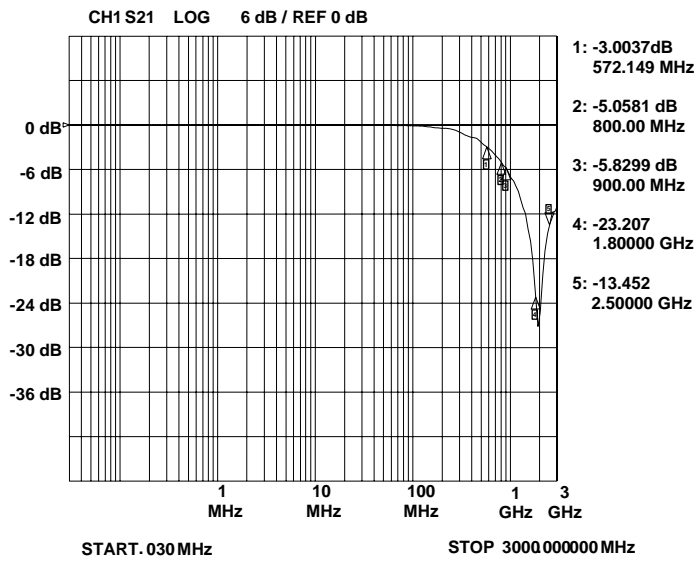
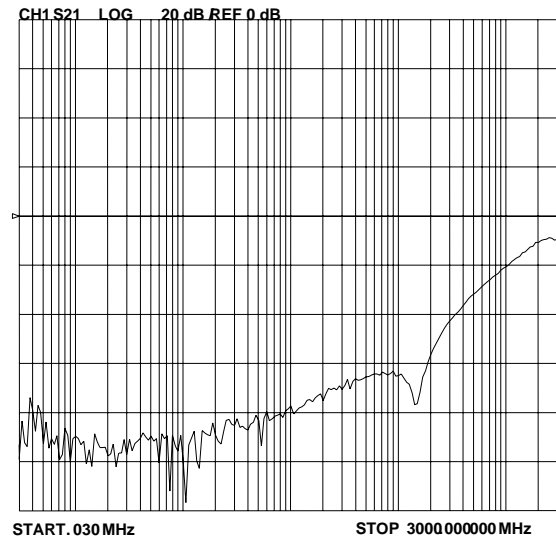


Junction Capacitance vs. Reverse Voltage



ESD Clamping
(8kV Contact per IEC 61000-4-2)



PROTECTION PRODUCTS
Typical Characteristics
Insertion Loss S21

Analog Crosstalk


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Applications Information

Device Connection Options

This device is designed to protect eight data lines. The device is unidirectional and may be used on lines where the signal polarity is above ground.

Ground Connection Recommendation

Parasitic inductance present in the board layout will affect the filtering and ESD performance of the device. Ground loop inductance can be reduced by using multiple vias to make the connection to the ground plane. Figure 2 shows the recommended device layout. The ground pad vias have a diameter of 0.008 inches (0.20 mm) while the two external vias have a diameter of 0.010 inches (0.250mm). The internal vias are spaced approximately evenly from the center of the pad. The designer may choose to use more vias with a smaller diameter (such as 0.005 inches or 0.125mm) since changing the diameter of the via will result in little change in inductance.

Circuit Board Layout Recommendations for Suppression of ESD.

Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

- Place the TVS near the input terminals or connectors to restrict transient coupling.
- Minimize the path length between the TVS and the protected line.
- Minimize all conductive loops including power and ground loops.
- The ESD transient return path to ground should be kept as short as possible.
- Never run critical signals near board edges.
- Use ground planes whenever possible.

Figure 1 - Circuit Diagram (Eight Each)

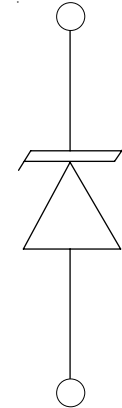
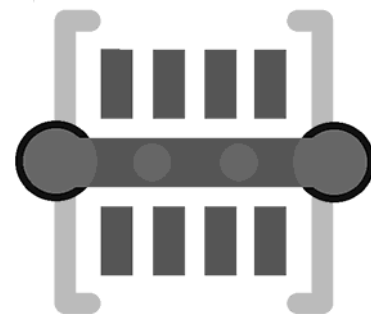
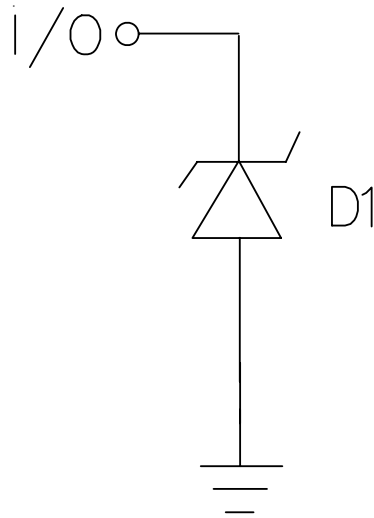


Figure 2 - Recommended Layout using Ground Vias

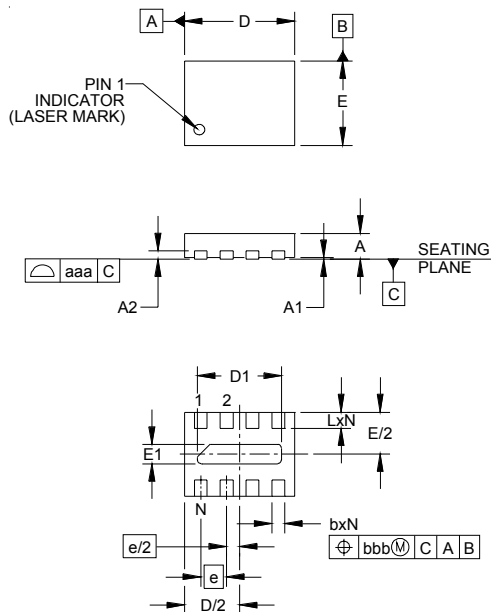


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Applications Information - Spice Model

uClamp0508T Spice Model

uClamp0508T Spice Parameters		
Parameter	Unit	D1 (TVS)
IS	Amp	2.05e-15
BV	Volt	7.0
VJ	Volt	0.80
RS	Ohm	0.75
IBV	Amp	1.0E-3
CJO	Farad	9e-12
TT	sec	2.541E-9
M	--	0.25
N	--	1.1
EG	eV	1.11

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Outline Drawing - SLP1713P8T

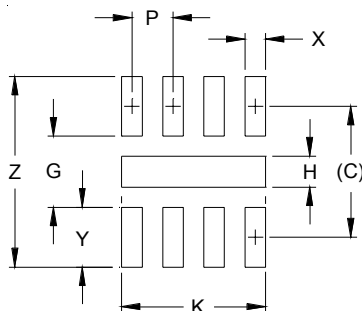


DIM	INCHES		MILLIMETERS	
	MIN	NOM/MAX	MIN	NOM/MAX
A	.015	.016 .017	0.37	0.40 0.43
A1	.000	.001 .002	0.00	0.02 0.05
A2		(.005)		(0.13)
b	.006	.008 .010	0.15	0.20 0.25
D	.065	.067 .070	1.65	1.70 1.78
D1	.047	.051 .055	1.20	1.30 1.40
E	.049	.051 .054	1.25	1.30 1.38
E1	.008	.012 .016	0.20	0.30 0.40
e	.016 BSC		0.40 BSC	
L	.008	.010 .012	0.20	0.25 0.30
N	8		8	
aaa	.003		0.08	
bbb	.004		0.10	

NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

Land Pattern - SLP1713P8T



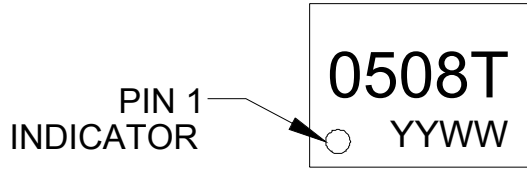
DIM	DIMENSIONS	
	INCHES	MILLIMETERS
C	(.050)	(1.27)
G	.027	0.69
H	.012	0.30
K	.055	1.40
P	.016	0.40
X	.008	0.20
Y	.023	0.58
Z	.073	1.85

NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.
3. THERMAL VIAS IN THE LAND PATTERN OF THE EXPOSED PAD SHALL BE CONNECTED TO A SYSTEM GROUND PLANE. FAILURE TO DO SO MAY COMPROMISE THE THERMAL AND/OR FUNCTIONAL PERFORMANCE OF THE DEVICE.

PROTECTION PRODUCTS

Marking Code



Ordering Information

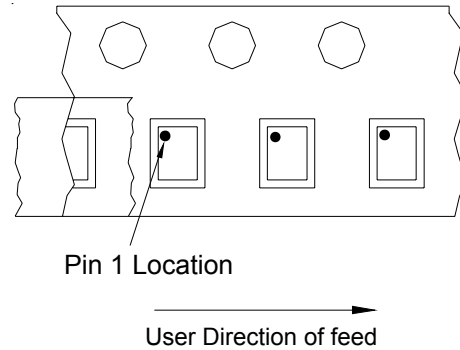
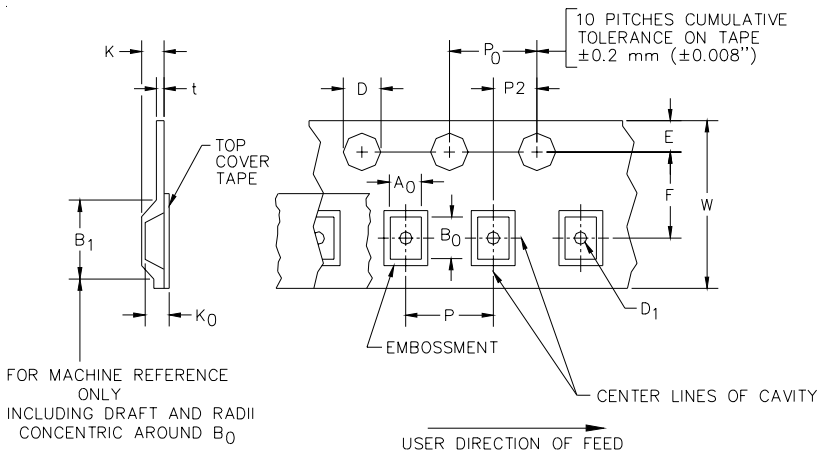
Part Number	Working Voltage	Qty per Reel	Reel Size
uClamp0508T.TCT	5V	3,000	7 Inch

Notes:

1) This is a lead-free, RoHS/WEEE compliant product
MicroClamp, uClamp and μ Clamp are marks of Semtech Corporation

Note: YYWW = Date Code

Tape and Reel Specification



Device Orientation in Tape

A0	B0	K0
1.51 +/-0.10 mm	1.91 +/-0.10 mm	0.66 +/-0.10 mm

Tape Width	B, (Max)	D	D1	E	F	K (MAX)	P	P0	P2	T(MAX)	W
8 mm	4.2 mm (.165)	1.5 + 0.1 mm - 0.0 mm (0.59 +.005 - .000)	0.8 mm ±0.05 (.031)	1.750±.10 mm (.069±.004)	3.5±0.05 mm (.138±.002)	2.4 mm (.094)	4.0±0.1 mm (.157±.004)	4.0±0.1 mm (.157±.004)	2.0±0.05mm (.079±.002)	0.4 mm (.016)	8.0 mm + 0.3 mm - 0.1 mm (.312±.012)

Contact Information

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